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# Selected Papers from ICAM2016 and ICI2016

Guest Editor:

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# Message from the Guest Editor

Dear Colleagues,

This Special Issue will select the papers related to invention/innovation advanced manufacturing, especially smart manufacturing, from ICI2016 (2016 2<sup>nd</sup> International Conference on Inventions. http://sciforum.net/conference/ICI2016) and ICAM 2016 (2016)International Conference on Advanced Manufacturing, http://sciforum.net/conference/ICAM2016). Smart manufacturing focuses on new and emerging technologies for industry 4.0. Papers with innovative ideas or research results in all aspects of advanced manufacture are also encouraged.

Prof. Dr. Chien-Hung Liu *Guest Editor* 



**Special**sue





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